

## **RJL6020DPK-VB Datasheet** N-Channel 600 V (D-S) Super Junction Power MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	600			
R <sub>DS(on)</sub> at 25 °C (Ω)	V <sub>GS</sub> = 10 V	0.23		
Q <sub>g</sub> Typ. (nC)	24			
Q <sub>gs</sub> (nC)	6			
Q <sub>gd</sub> (nC)	11			
Configuration	Single			

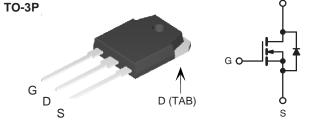
#### **FEATURES**

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- Reduced switching and conduction losses
- Ultra low gate charge (Q<sub>a</sub>)
- Avalanche energy rated (UIS)



#### **APPLICATIONS**

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Renewable energy
  - Solar (PV inverters)



N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			$V_{DS}$	600	V	
Gate-Source Voltage			$V_{GS}$	± 30	V	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 25 °C	- I <sub>D</sub>	15		
		T <sub>C</sub> = 100 °C		10	Α	
Pulsed Drain Current <sup>a</sup>			I <sub>DM</sub>	45		
Linear Derating Factor				1.4	W/°C	
Single Pulse Avalanche Energy b			E <sub>AS</sub>	286	mJ	
Maximum Power Dissipation			P <sub>D</sub>	180	W	
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	
Drain-Source Voltage Slope	T <sub>J</sub> = 125 °C		-I\	37	\//na	
Reverse Diode dV/dt <sup>d</sup>		dV/dt	23	- V/ns		
Soldering Recommendations (Peak Temperature) c	for 10 s			300	°C	

- a. Repetitive rating; pulse width limited by maximum junction temperature. b.  $V_{DD}=50$  V, starting T<sub>J</sub> = 25 °C, L = 28.2 mH, R<sub>g</sub> = 25  $\Omega$ , I<sub>AS</sub> = 4.5 A.
- c. 1.6 mm from case.
- d.  $I_{SD} \le I_D$ , dI/dt = 100 A/ $\mu$ s, starting  $T_J = 25$  °C.

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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	TYP. MAX.		
Maximum Junction-to-Ambient	R <sub>thJA</sub>	-	62	°C/W	
Maximum Junction-to-Case (Drain)	R <sub>thJC</sub>	-	0.7	C/VV	

PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static		•					•
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		600	-	-	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	Reference to 25 °C, I <sub>D</sub> = 1 mA		0.75	-	V/°C
Gate-Source Threshold Voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$		-	4	V
			V <sub>GS</sub> = ± 20 V	-	-	± 100	nA
Gate-Source Leakage	$I_{GSS}$	$V_{GS} = \pm 30 \text{ V}$		-	-	± 1	μΑ
		V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V V <sub>DS</sub> = 520 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C		-	-	1	μΑ
Zero Gate Voltage Drain Current	$I_{DSS}$			-	_	10	
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 8 A	-	0.23	-	Ω
Forward Transconductance	9fs	V <sub>DS</sub> = 30 V, I <sub>D</sub> = 8 A		-	5.6	-	S
Dynamic		,					
Input Capacitance	C <sub>iss</sub>	$V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$ $f = 1 \text{ MHz}$		-	1640	-	pF
Output Capacitance	Coss			-	80	-	
Reverse Transfer Capacitance	C <sub>rss</sub>			-	4	-	
Effective Output Capacitance, Energy Related <sup>a</sup>	C <sub>o(er)</sub>	V <sub>DS</sub> = 0 V to 520 V, V <sub>GS</sub> = 0 V		-	63		
Effective Output Capacitance, Time Related <sup>b</sup>	C <sub>o(tr)</sub>			-	213	-	
Total Gate Charge	Qg			-	24	48	
Gate-Source Charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V I <sub>D</sub> = 8 A, V <sub>DS</sub> = 520 V		-	6	-	nC
Gate-Drain Charge	Q <sub>gd</sub>				11	-	
Turn-On Delay Time	t <sub>d(on)</sub>	$V_{DD}$ = 520V, I $_{D}$ = 8 A, $V_{GS}$ = 10 V, R $_{g}$ = 9.1 $\Omega$		-	18	36	ns
Rise Time	t <sub>r</sub>			-	24	48	
Turn-Off Delay Time	t <sub>d(off)</sub>			-	48	96	
Fall Time	t <sub>f</sub>			-	25	50	
Gate Input Resistance	$R_{g}$	f = 1 MHz, open drain		-	0.8	-	Ω
<b>Drain-Source Body Diode Characteristic</b>	S						
Continuous Source-Drain Diode Current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	15	
Pulsed Diode Forward Current	I <sub>SM</sub>			-	-	38	- A
Diode Forward Voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 8 A, V <sub>GS</sub> = 0 V		-	-	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C, I <sub>F</sub> = I <sub>S</sub> = 8 A, dl/dt = 100 A/μs, V <sub>R</sub> = 400 V		-	325	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>			-	4.6	-	μC
Reverse Recovery Current	I <sub>RBM</sub>			_	20	_	A

#### Notes

- a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ . b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .

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#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

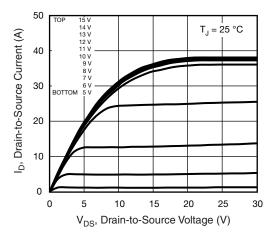


Fig. 1 - Typical Output Characteristics

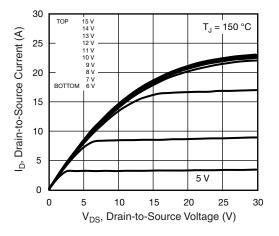


Fig. 2 - Typical Output Characteristics

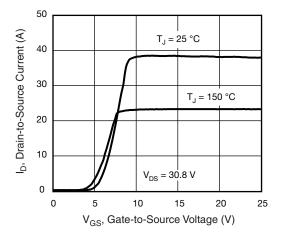


Fig. 3 - Typical Transfer Characteristics

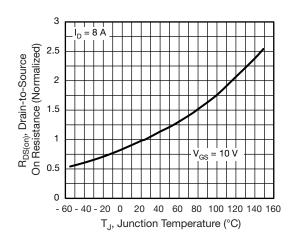


Fig. 4 - Normalized On-Resistance vs. Temperature

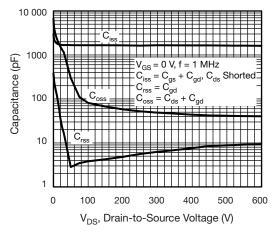


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

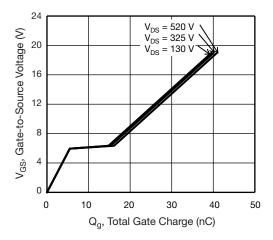


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



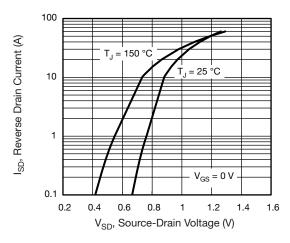


Fig. 7 - Typical Source-Drain Diode Forward Voltage

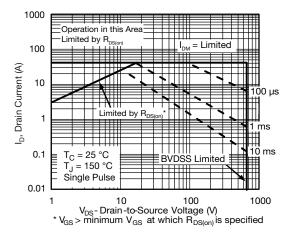


Fig. 8 - Maximum Safe Operating Area

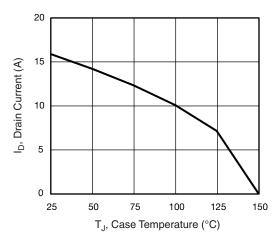


Fig. 9 - Maximum Drain Current vs. Case Temperature

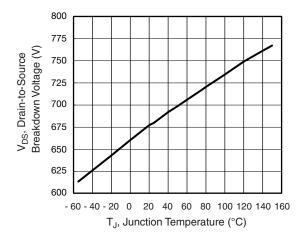


Fig. 10 - Temperature vs. Drain-to-Source Voltage

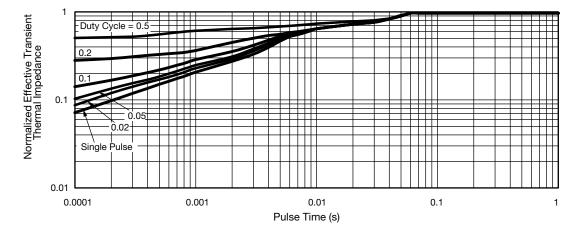


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case

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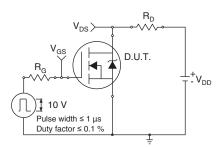


Fig. 12 - Switching Time Test Circuit

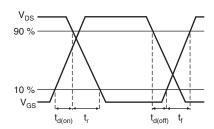


Fig. 13 - Switching Time Waveforms

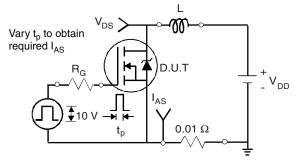


Fig. 14 - Unclamped Inductive Test Circuit

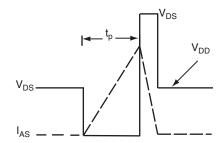


Fig. 15 - Unclamped Inductive Waveforms

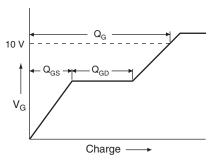


Fig. 16 - Basic Gate Charge Waveform

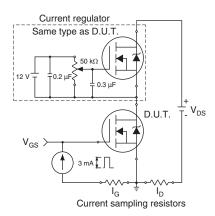
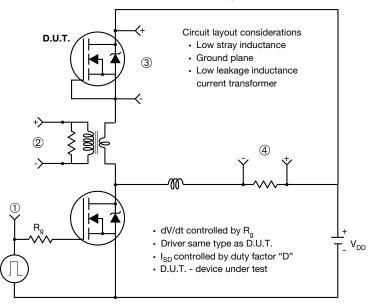


Fig. 17 - Gate Charge Test Circuit

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### Peak Diode Recovery dV/dt Test Circuit



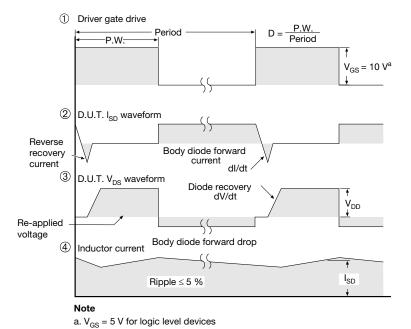
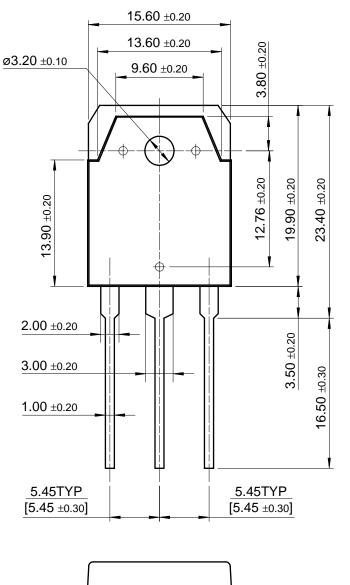


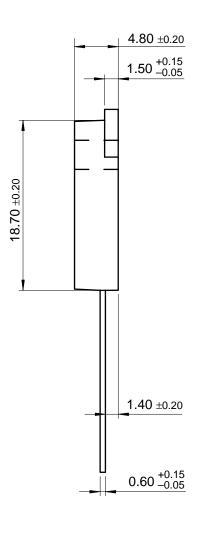
Fig. 18 - For N-Channel

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